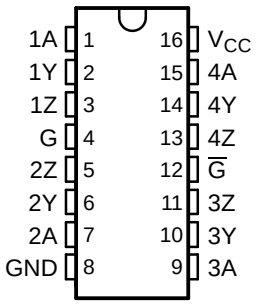
26LS31-SMD
QUADRUPLE DIFFERENTIAL LINE DRIVER

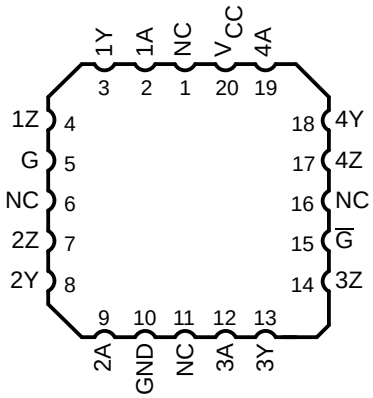
FEATURES

- **Meets or Exceeds the Requirements of ANSI TIA/EIA-422-B and ITU**
- **Operates From a Single 5-V Supply**
- **TTL Compatible**
- **Complementary Outputs**
- **High Output Impedance in Power-Off Conditions**
- **Complementary Output-Enable Inputs**

D, DB, N, NS, J, OR W PACKAGE
(TOP VIEW)



FK PACKAGE
(TOP VIEW)



DESCRIPTION/ORDERING INFORMATION

The AM26LS31 is a quadruple complementary-output line driver designed to meet the requirements of ANSI TIA/EIA-422-B and ITU (formerly CCITT) Recommendation V.11. The 3-state outputs have high-current capability for driving balanced lines such as twisted-pair or parallel-wire transmission lines, and they are in the high-impedance state in the power-off condition. The enable function is common to all four drivers and offers the choice of an active-high or active-low enable (G, $\overline{G}$) input. Low-power Schottky circuitry reduces power consumption without sacrificing speed.

ORDERING INFORMATION

T_A	PACKAGE(1)		ORDERABLE PART NUMBER	TOP-SIDE MARKING
0°C to 70°C	PDIP – N	Tube	AM26LS31CN	AM26LS31CN
	SOIC – D	Tube	AM26LS31CD	AM26LS31C
		Tape and reel	AM26LS31CDR	
	SOP – NS	Tape and reel	AM26LS31CNSR	26LS31
	SSOP – DB	Tape and reel	AM26LS31CDBR	SA31C
–55°C to 125°C	CDIP – J	Tube	AM26LS31MJB	AM26LS31MJB
	LCCC – FK	Tube	AM26LS31MFKB	AM26LS31MFKB
	CFP – W	Tube	AM26LS31MWB	AM26LS31MWB

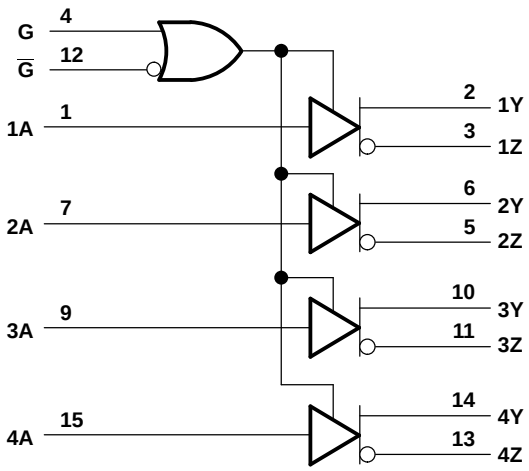
(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE (1) (EACH DRIVER)

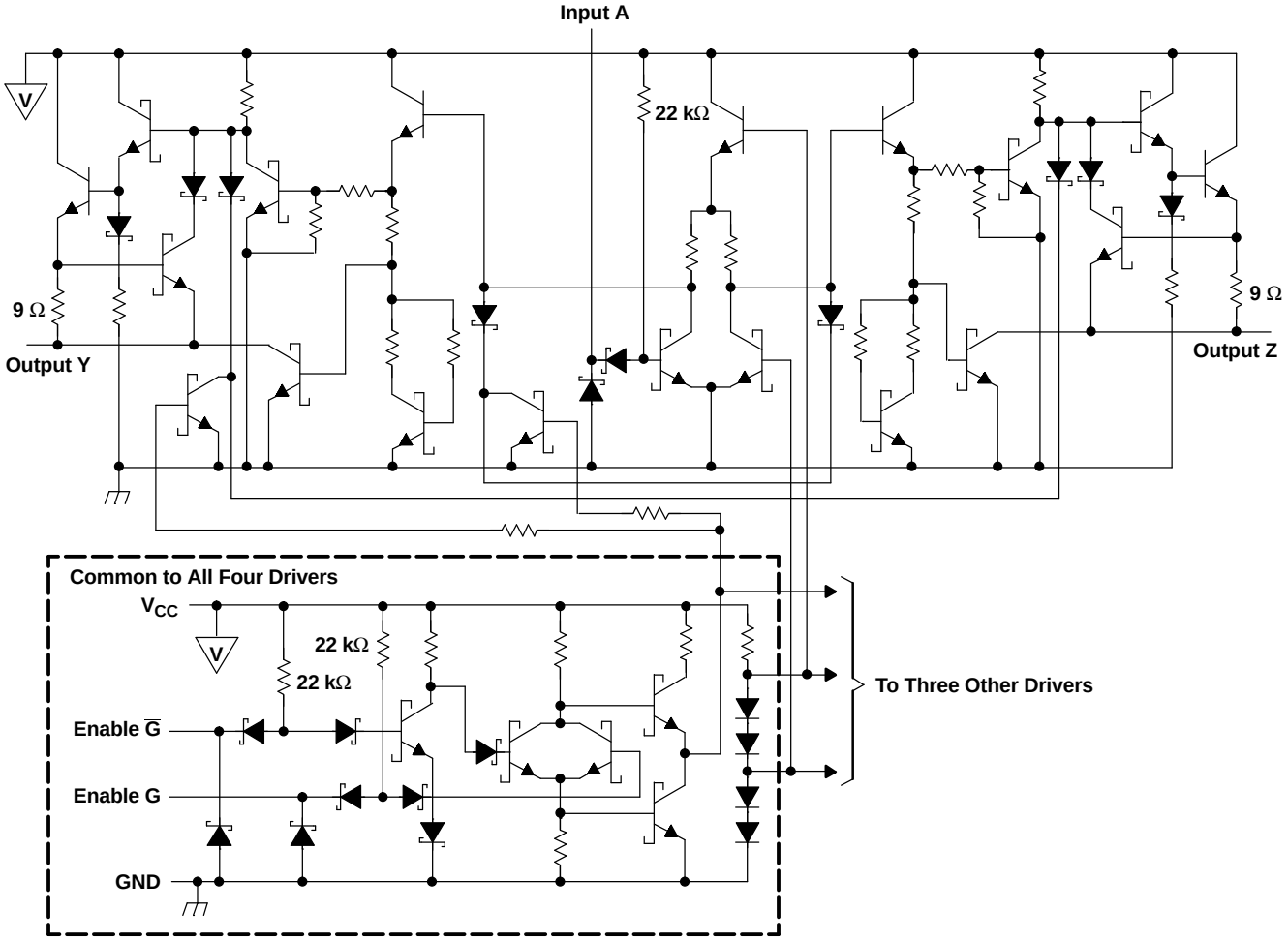
INPUT A	ENABLES		OUTPUTS	
	G	$\overline{G}$	Y	Z
H	H	X	H	L
L	H	X	L	H
H	X	L	H	L
L	X	L	L	H
X	L	H	Z	Z

(1) H = high level, L = low level,
X = irrelevant,
Z = high impedance (off)

LOGIC DIAGRAM (POSITIVE LOGIC)



SCHEMATIC (EACH DRIVER)



All resistor values are nominal.

Absolute Maximum Ratings(1)

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V_{CC}	Supply voltage(2)			7	V
V_I	Input voltage			7	V
	Output off-state voltage			5.5	V
θ_{JA}	Package thermal impedance(3)	D package		73	°C/W
		DB package		82	
		N package		67	
		NS package		64	
	Lead temperature 1,6 mm (1/16 in) from case for 10 s			260	°C
	Lead temperature 1,6 mm (1/16 in) from case for 60 s	J package		300	°C
T_{stg}	Storage temperature range		–65	150	°C

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
(2) All voltage values, except differential output voltage V_{OD}, are with respect to network GND.
(3) The package thermal impedance is calculated in accordance with JESD 51-7.

Recommended Operating Conditions

			MIN	NOM	MAX	UNIT
V_{CC}	Supply voltage	AM26LS31C	4.75	5	5.25	V
		AM26LS31M	4.5	5	5.5	
V_{IH}	High-level input voltage		2			V
V_{IL}	Low-level input voltage				0.8	V
I_{OH}	High-level output current				–20	mA
I_{OL}	Low-level output current				20	mA
T_A	Operating free-air temperature	AM26LS31C	0		70	°C
		AM26LS31M	–55		125	

Electrical Characteristics(1)

over operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP(2)	MAX	UNIT
V_{IK}	Input clamp voltage	V_{CC} = MIN,	I_I = –18 mA			–1.5	V
V_{OH}	High-level output voltage	V_{CC} = MIN,	I_{OH} = –20 mA	2.5			V
V_{OL}	Low-level output voltage	V_{CC} = MIN,	I_{OL} = 20 mA			0.5	V
I_{OZ}	Off-state (high-impedance-state) output current	V_{CC} = MIN,	V_O = 0.5 V			–20	µA
			V_O = 2.5 V			20	
I_I	Input current at maximum input voltage	V_{CC} = MAX,	V_I = 7 V			0.1	mA
I_{IH}	High-level input current	V_{CC} = MAX,	V_I = 2.7 V			20	µA
I_{IL}	Low-level input current	V_{CC} = MAX,	V_I = 0.4 V			–0.36	mA
I_{OS}	Short-circuit output current(3)	V_{CC} = MAX		–30		–150	mA
I_{CC}	Supply current	V_{CC} = MAX,	All outputs disabled		32	80	mA

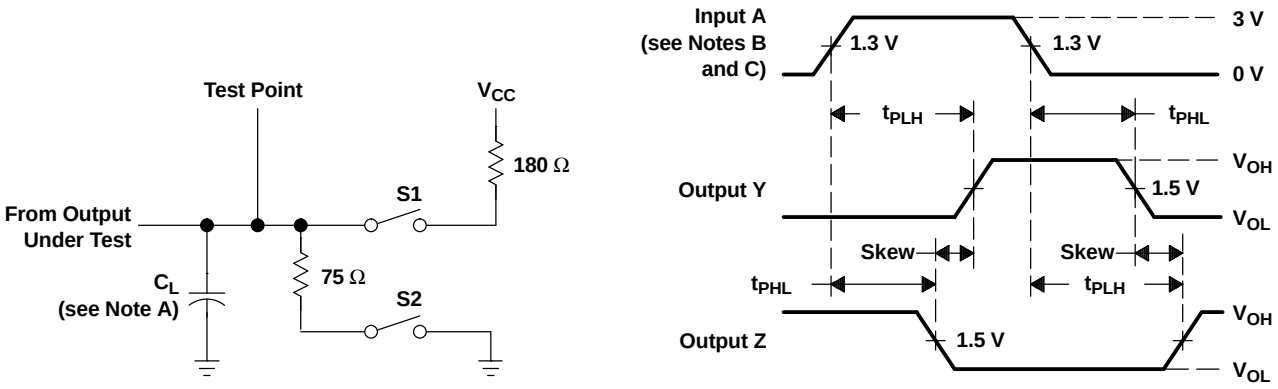
(1) For C-suffix devices, V_{CC} min = 4.75 V and V_{CC} max = 5.25 V. For M-suffix devices, V_{CC} min = 4.5 V and V_{CC} max = 5.5 V.
(2) All typical values are at V_{CC} = 5 V and T_A = 25°C.
(3) Not more than one output should be shorted at a time, and duration of the short circuit should not exceed one second.

Switching Characteristics

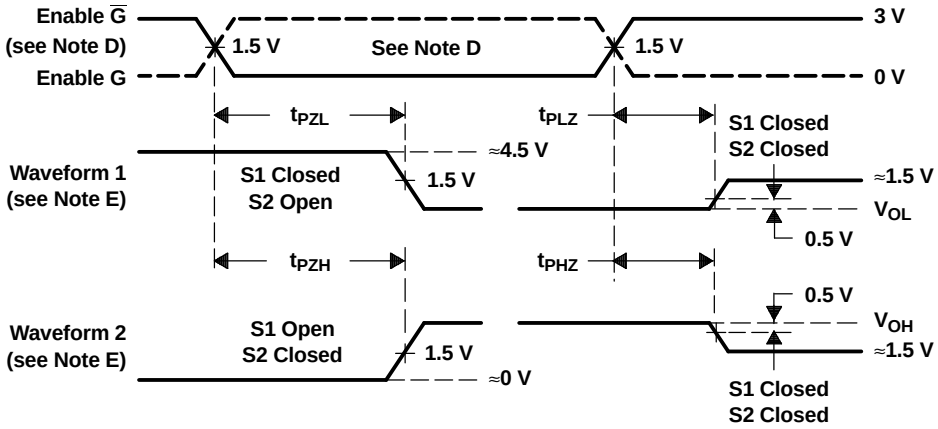
V_{CC} = 5 V (see Figure 1)

PARAMETER		TEST CONDITIONS		T_A = 25°C			AM26LS31M		UNIT
				MIN	TYP	MAX	MIN	MAX	
t_{PLH}	Propagation delay time, low- to high-level output	C_L = 30 pF,	S1 and S2 open		14	20		30	ns
t_{PHL}	Propagation delay time, high- to low-level output				14	20		30	
t_{PZH}	Output enable time to high level	C_L = 30 pF	R_L = 75 Ω		25	40		60	ns
t_{PZL}	Output enable time to low level		R_L = 180 Ω		37	45		68	
t_{PHZ}	Output disable time from high level	C_L = 10 pF,	S1 and S2 closed		21	30		45	ns
t_{PLZ}	Output disable time from low level				23	35		53	
t_{SKEW}	Output-to-output skew	C_L = 30 pF,	S1 and S2 open		1	6		9	ns

PARAMETER MEASUREMENT INFORMATION



PROPAGATION DELAY TIMES AND SKEW **TEST CIRCUIT**



ENABLE AND DISABLE TIME WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.
B. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, Z_O ≈ 50 Ω, t_r ≤ 15 ns, t_f ≤ 6 ns.
C. When measuring propagation delay times and skew, switches S1 and S2 are open.
D. Each enable is tested separately.
E. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.

Figure 1. Test Circuit and Voltage Waveforms

TYPICAL CHARACTERISTICS

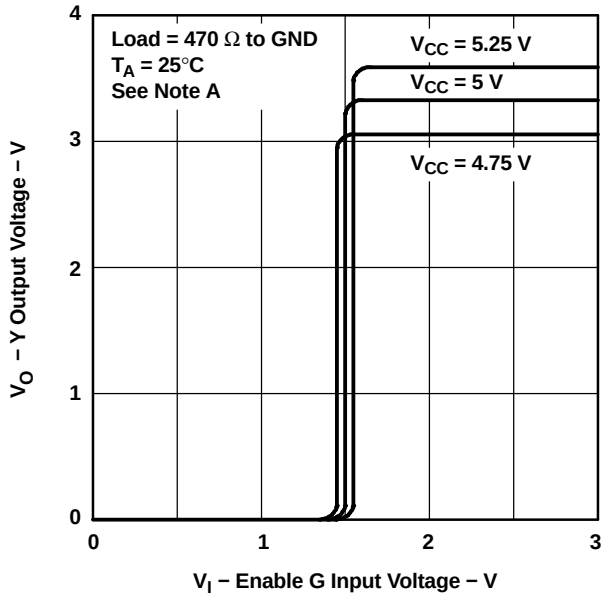


Figure 2.

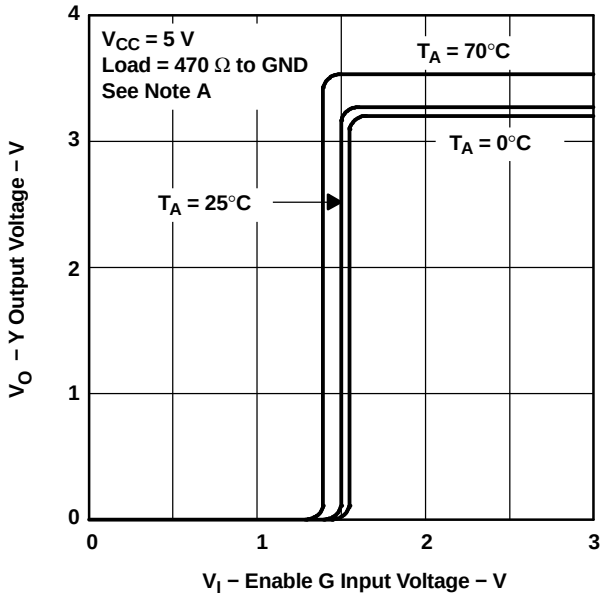


Figure 3.

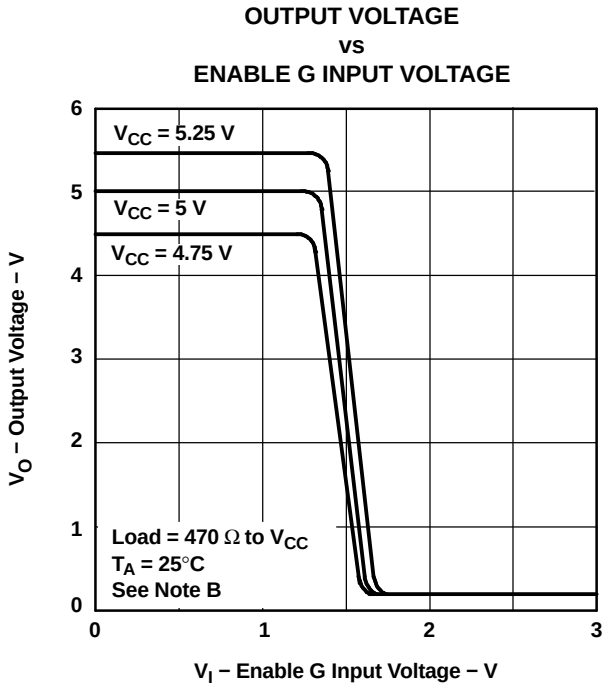


Figure 4.

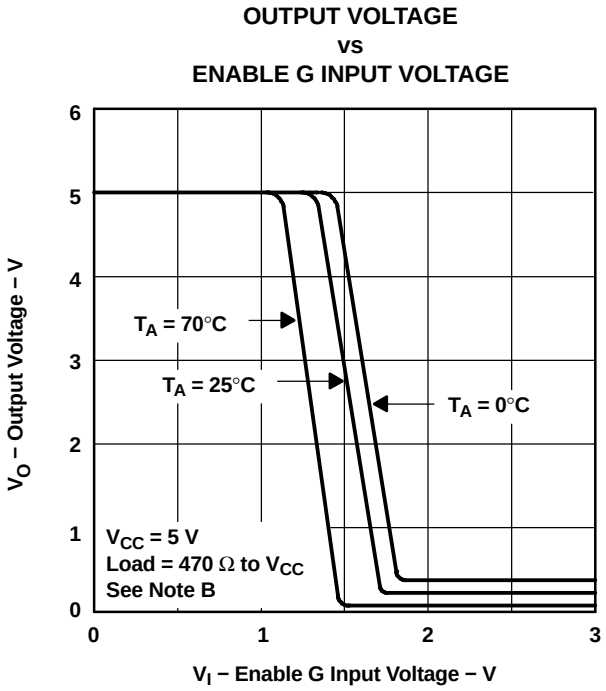


Figure 5.

A. The A input is connected to V_{CC} during testing of the Y outputs and to ground during testing of the Z outputs.

B. The A input is connected to ground during testing of the Y outputs and to V_{CC} during testing of the Z outputs.

TYPICAL CHARACTERISTICS (continued)

HIGH-LEVEL OUTPUT VOLTAGE vs FREE-AIR TEMPERATURE

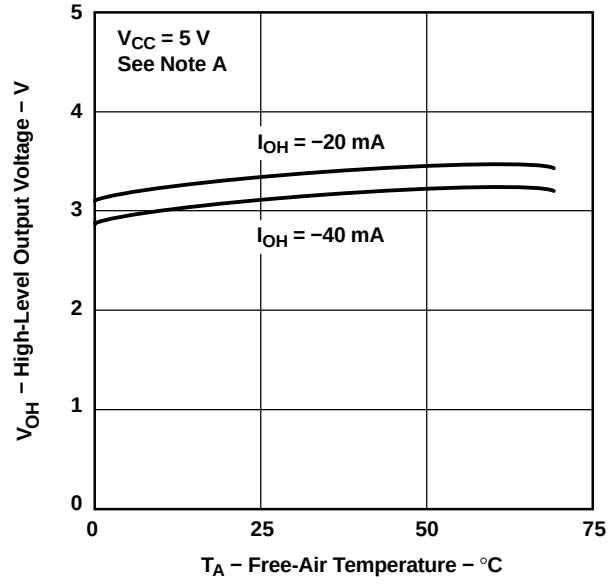


Figure 6.

HIGH-LEVEL OUTPUT VOLTAGE vs HIGH-LEVEL OUTPUT CURRENT

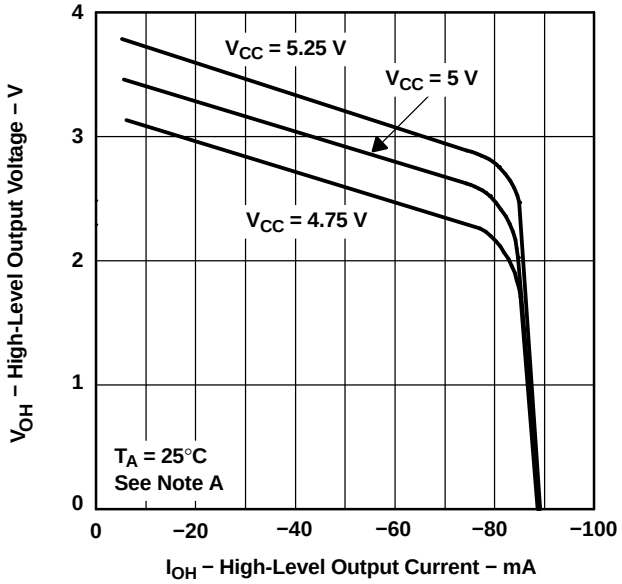


Figure 7.

LOW-LEVEL OUTPUT VOLTAGE vs FREE-AIR TEMPERATURE

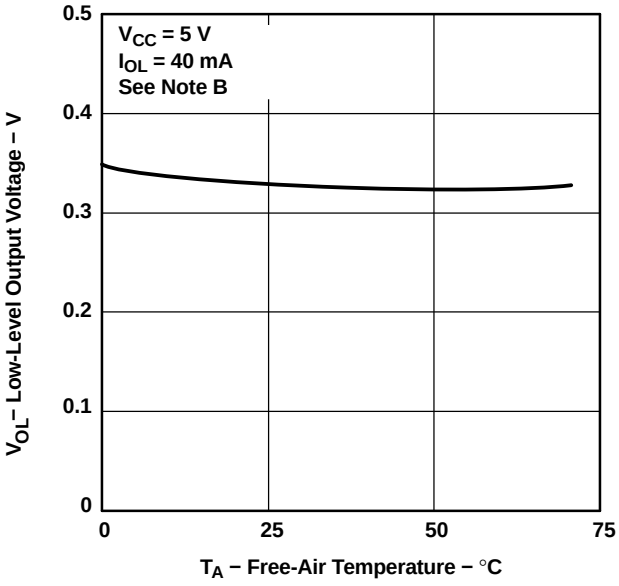


Figure 8.

LOW-LEVEL OUTPUT VOLTAGE vs LOW-LEVEL OUTPUT CURRENT

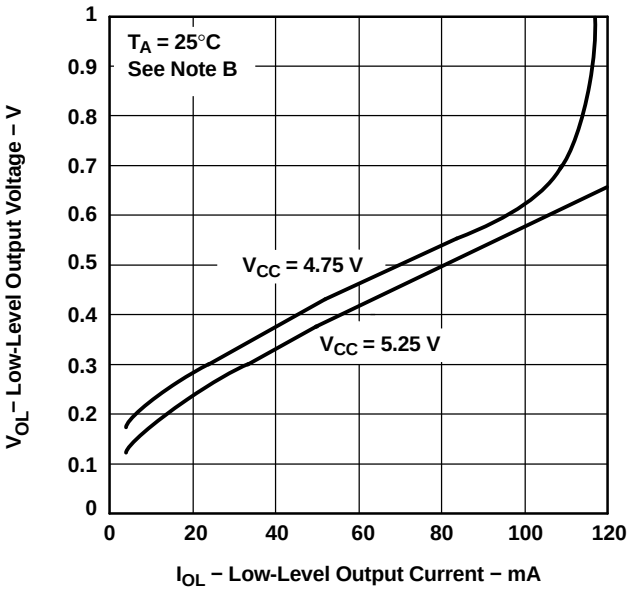


Figure 9.

A. The A input is connected to V_{CC} during testing of the Y outputs and to ground during testing of the Z outputs.

B. The A input is connected to ground during testing of the Y outputs and to V_{CC} during testing of the Z outputs.

TYPICAL CHARACTERISTICS (continued)

Y OUTPUT VOLTAGE vs DATA INPUT VOLTAGE

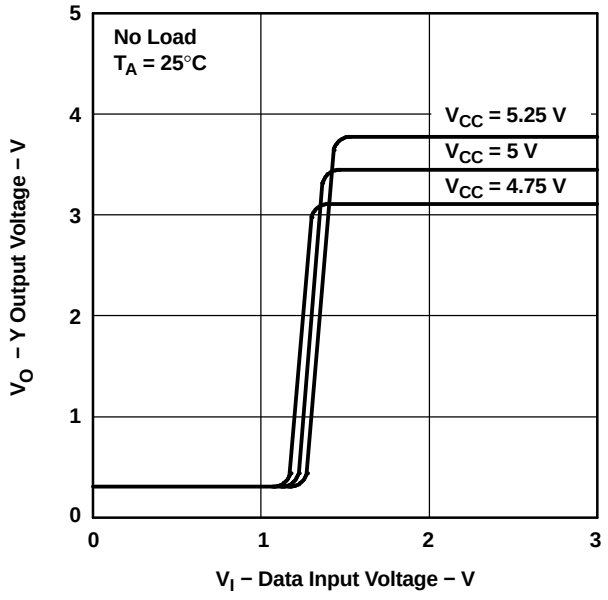


Figure 10.

Y OUTPUT VOLTAGE vs DATA INPUT VOLTAGE

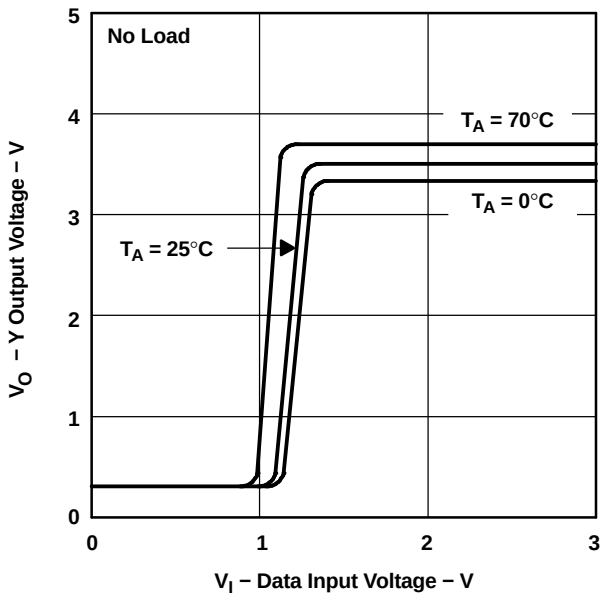


Figure 11.

PACKAGING INFORMATION

Orderable Device	Status [1]	Package Type	Package Drawing	Pins	Package Qty	Eco Plan [2]	Lead/Ball Finish	MSL Peak Temp [3]
5962-7802301M2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
5962-7802301MEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
5962-7802301MFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
AM26LS31CD	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
AM26LS31CDBR	ACTIVE	SSOP	DB	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
AM26LS31CDBRE4	ACTIVE	SSOP	DB	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
AM26LS31CDBRG4	ACTIVE	SSOP	DB	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
AM26LS31CDE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
AM26LS31CDG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
AM26LS31CDR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
AM26LS31CDRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
AM26LS31CDRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
AM26LS31CN	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
AM26LS31CNE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
AM26LS31CNSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
AM26LS31CNSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
AM26LS31MFKB	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
AM26LS31MJB	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
AM26LS31MWB	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type

[1] The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

[2] Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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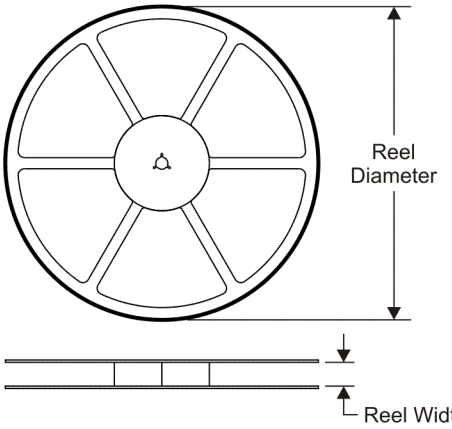
PACKAGE MATERIALS INFORMATION

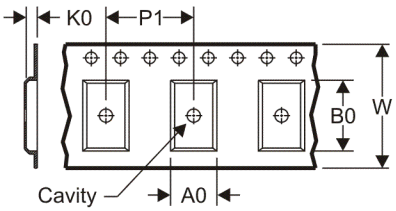
16-Jun-2009

TAPE AND REEL INFORMATION

REEL DIMENSIONS

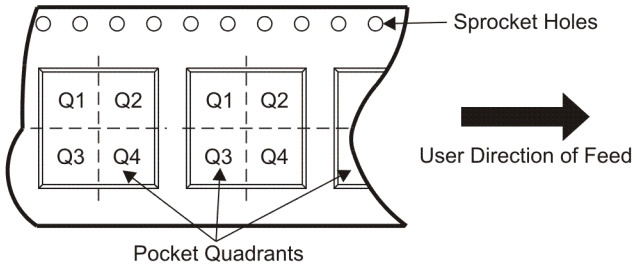


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



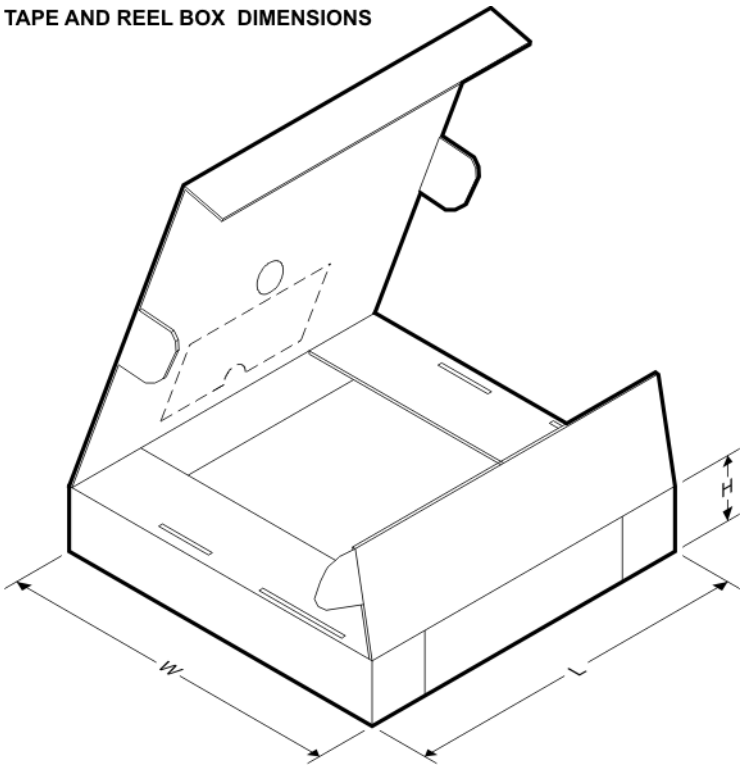
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
AM26LS31CDBR	SSOP	DB	16	2000	330.0	16.4	8.2	6.6	2.5	12.0	16.0	Q1
AM26LS31CDR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
AM26LS31CDR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
AM26LS31CNSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

PACKAGE MATERIALS INFORMATION

16-Jun-2009

TAPE AND REEL BOX DIMENSIONS



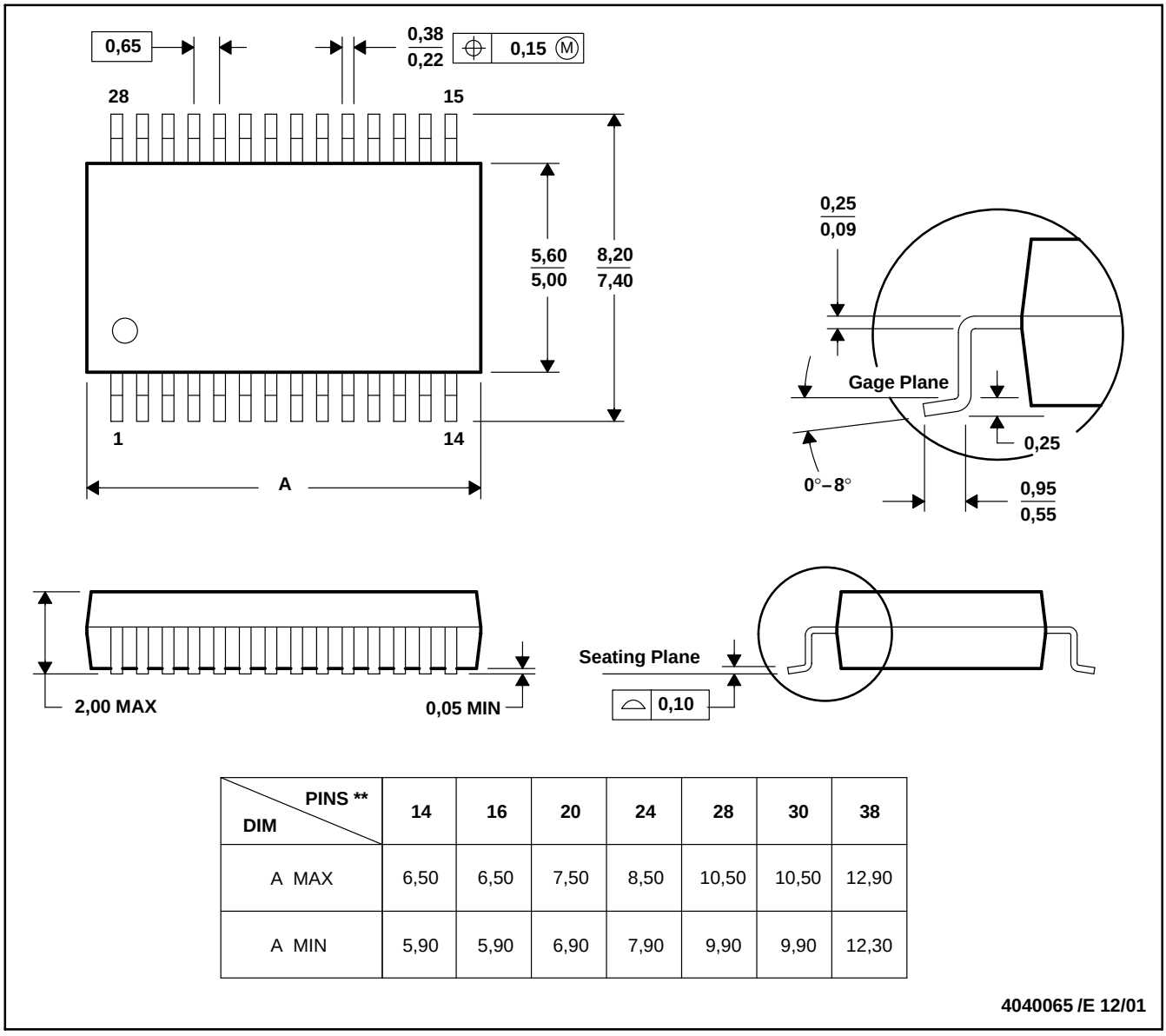
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
AM26LS31CDBR	SSOP	DB	16	2000	346.0	346.0	33.0
AM26LS31CDR	SOIC	D	16	2500	346.0	346.0	33.0
AM26LS31CDR	SOIC	D	16	2500	333.2	345.9	28.6
AM26LS31CNSR	SO	NS	16	2000	346.0	346.0	33.0

MSSO002E – JANUARY 1995 – REVISED DECEMBER 2001

DB (R-PDSO-G)** **PLASTIC SMALL-OUTLINE**

28 PINS SHOWN



DIM \ PINS **	14	16	20	24	28	30	38
A MAX	6,50	6,50	7,50	8,50	10,50	10,50	12,90
A MIN	5,90	5,90	6,90	7,90	9,90	9,90	12,30

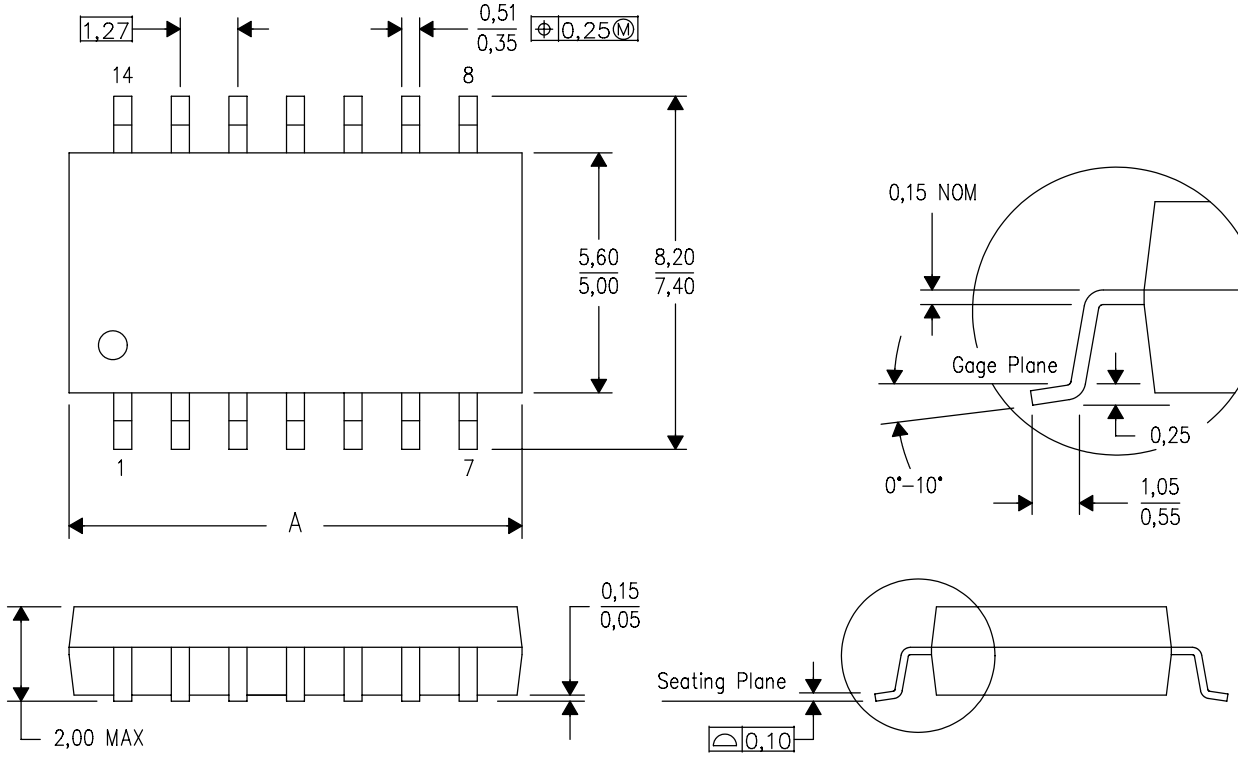
4040065 /E 12/01

NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
D. Falls within JEDEC MO-150

MECHANICAL DATA

NS (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

14-PINS SHOWN



DIM \ PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

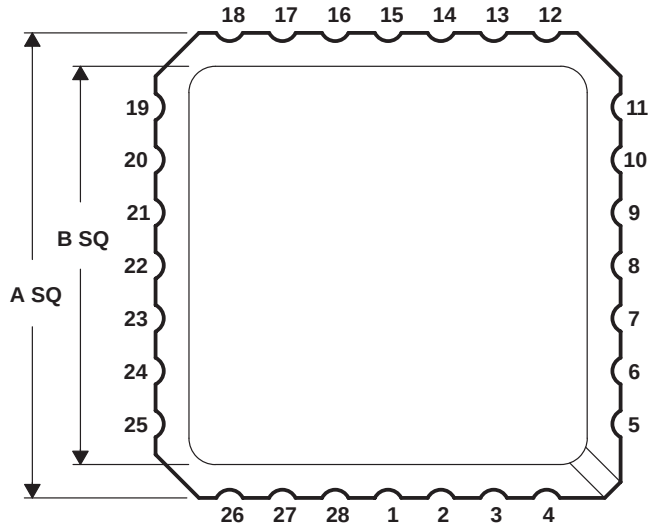
4040062/C 03/03

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

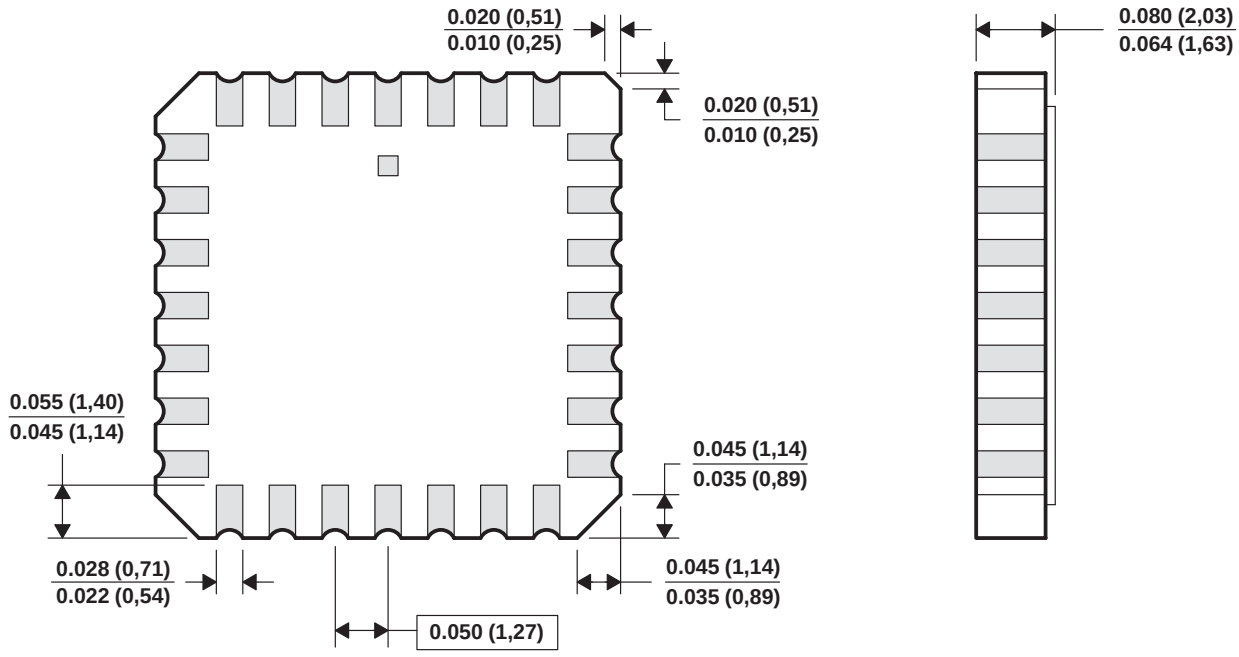
FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.739 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)



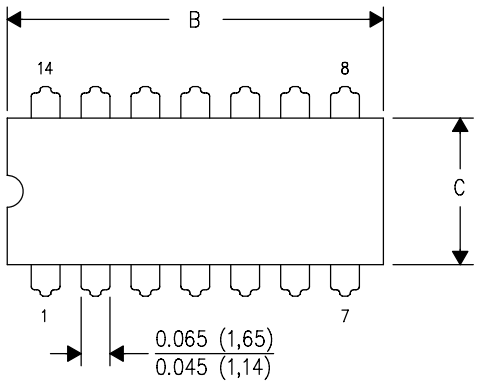
4040140/D 10/96

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a metal lid.
D. The terminals are gold plated.
E. Falls within JEDEC MS-004

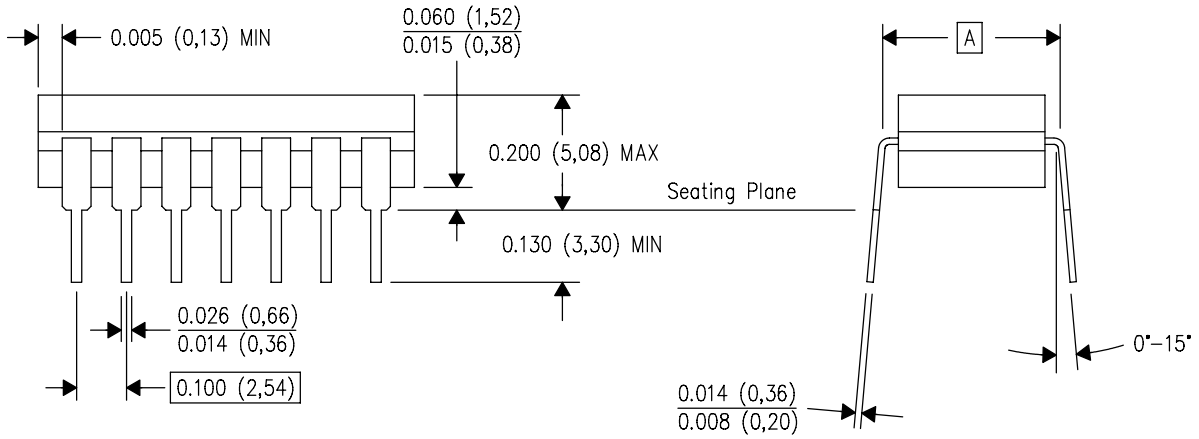
J (R–GDIP–T**)

14 LEADS SHOWN

CERAMIC DUAL IN–LINE PACKAGE



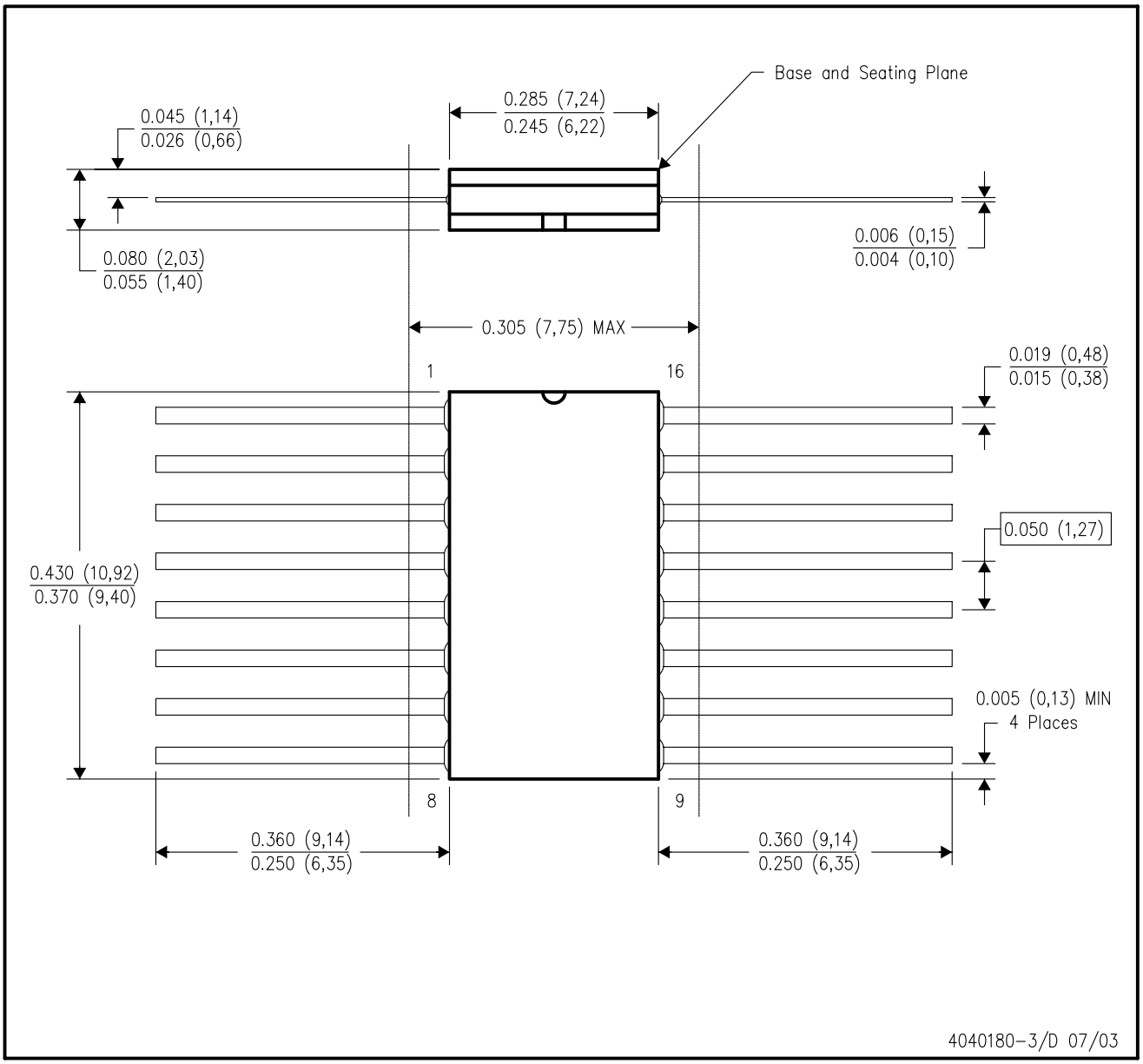
DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

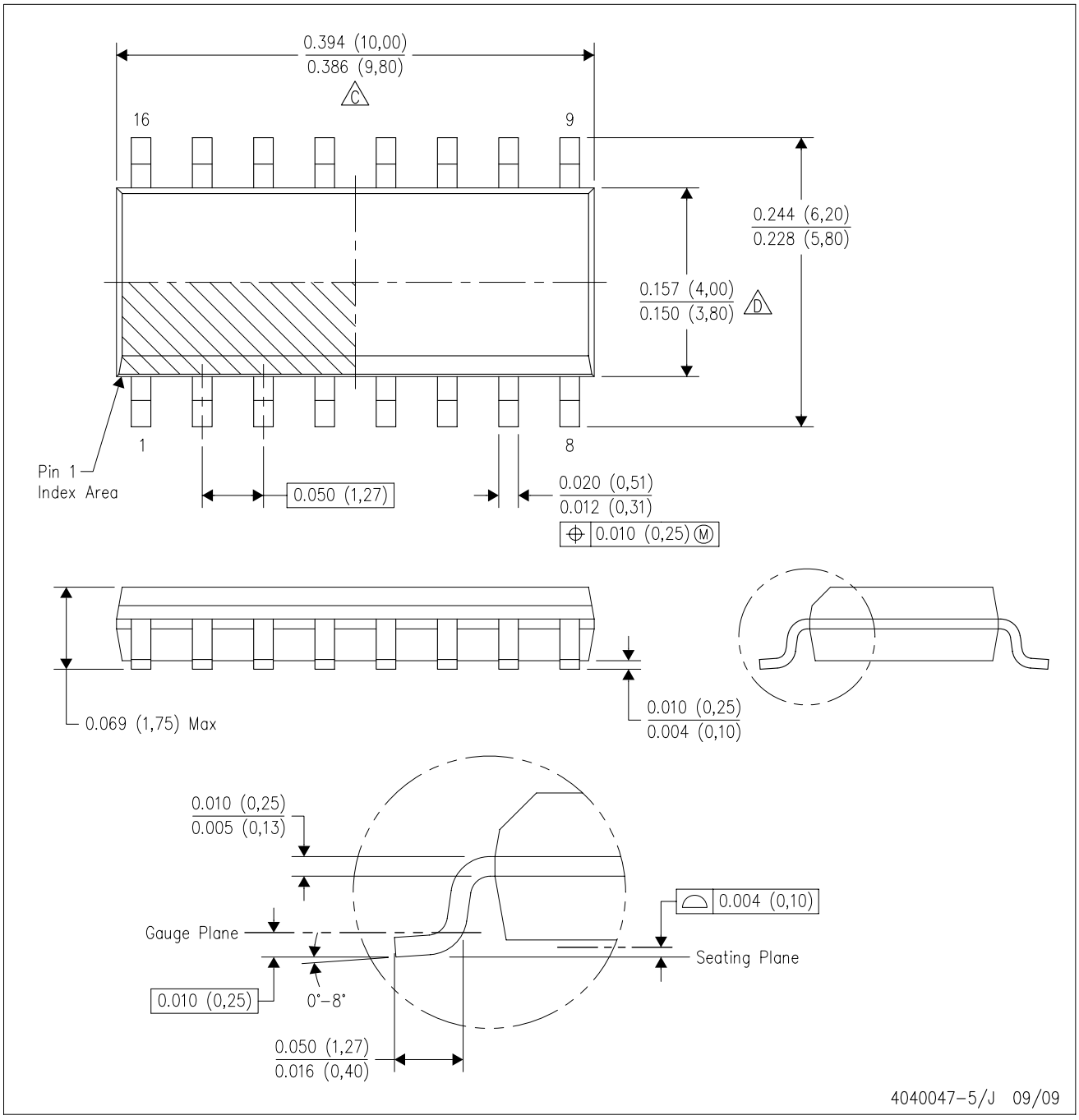
NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package is hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
E. Falls within MIL STD 1835 GDIP1–T14, GDIP1–T16, GDIP1–T18 and GDIP1–T20.

W (R–GDFP–F16) CERAMIC DUAL FLATPACK



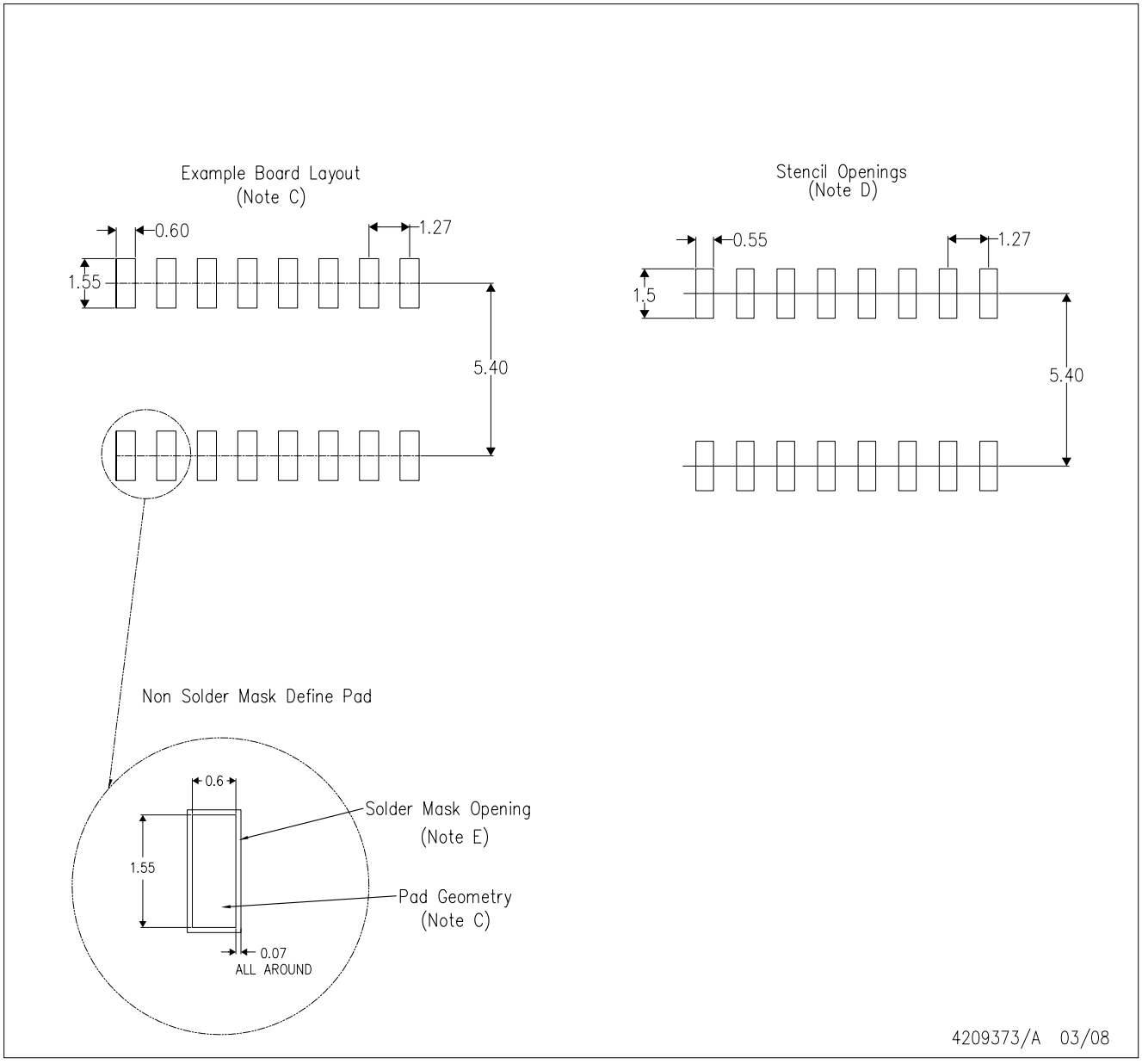
NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only.
E. Falls within MIL STD 1835 GDFP1–F16 and JEDEC MO–092AC

D (R–PDSO–G16) PLASTIC SMALL–OUTLINE PACKAGE



NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
D. Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
E. Reference JEDEC MS–012 variation AC.

D(R–PDSO–G16)

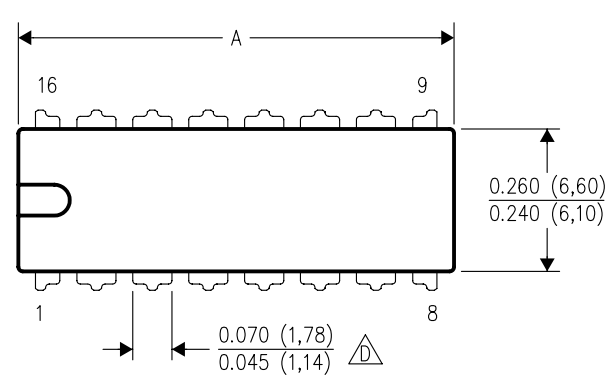


NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Refer to IPC7351 for alternate board design.
D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC–7525
E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

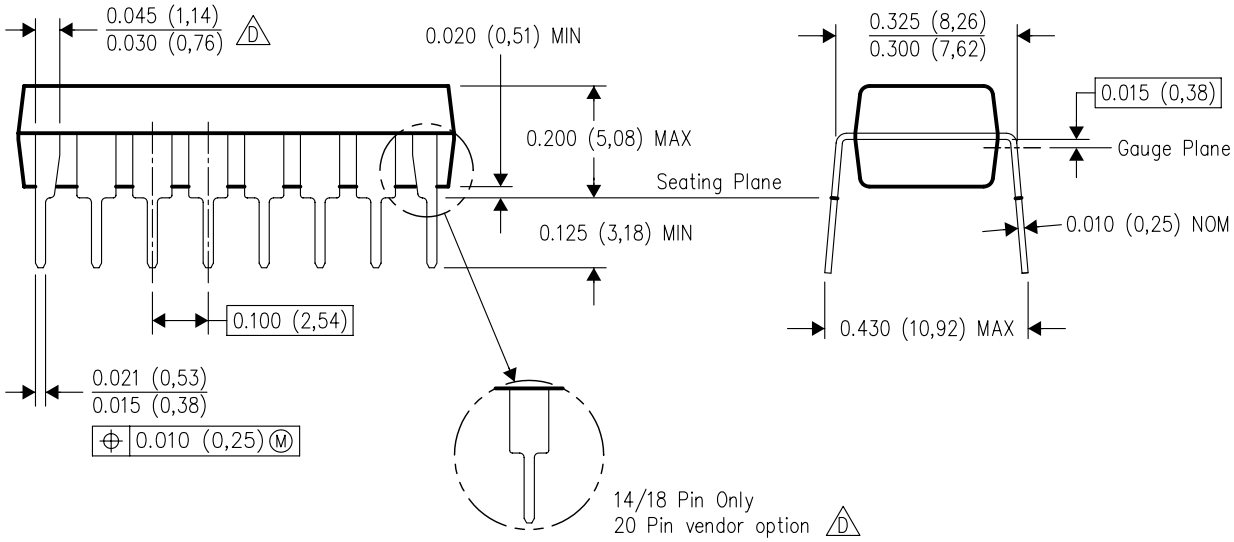
N (R–PDIP–T**)

PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN



DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS–001 VARIATION (C)	AA	BB	AC	AD



4040049/E 12/2002

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
D. The 20 pin end lead shoulder width is a vendor option, either half or full width.